

REG-00-012C

09/821,546

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August 30, 2006

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	09/821,546	03/30/2001
J. Y. LEE		
"A STRUCTURE AND MANUFACTURING METHOD OF CHIP SCALE PACKAGE"		
Grp. Art Unit: 2811	D. W. OWENS	

RESPONSE FINAL PATENT OFFICE ACTION

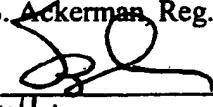
Dear Sir:

In response to the Final Office Action dated June 14, 2006, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 14, 2006.

Stephen B. Ackerman, Reg. No. 37,761

Signature 
Date 9/14/06